

# PATENT ASSIGNMENT

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Hideto Nakamura	09/12/2011
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Sumitomo Wiring Systems, Ltd.
<b>Street Address:</b>	1-14, Nishisuehiro-cho
<b>City:</b>	Yokkaichi-City, Mie
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	510-8503
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	13227672
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(212)725-2452
<b>Phone:</b>	2127252450
<b>Email:</b>	email@hpiplaw.com
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Correspondent Name:</b>	HESPOS & PORCO LLP
<b>Address Line 1:</b>	110 West 40th Street
<b>Address Line 2:</b>	Suite 2501
<b>Address Line 4:</b>	NEW YORK, NEW YORK 10018
<b>ATTORNEY DOCKET NUMBER:</b>	FP11-068US
<b>NAME OF SUBMITTER:</b>	Gerald E. Hespos
<b>Total Attachments: 1</b> source=FP11-068US#page1.tif	

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**PATENT**  
**REEL: 026927 FRAME: 0310**

**ASSIGNMENT**

In consideration of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned by the Assignee, Sumitomo Wiring Systems, Ltd., a corporation organized under the laws of Japan, located at 1-14, Nishisuehiro-cho, Yokkaichi-City, Mie, 510-8503 Japan, receipt whereof is hereby acknowledged, the undersigned by these presents hereby sells, assigns, transfers and sets over unto the said assignee the entire right, title and interest in and to the invention or improvement entitled "CONNECTOR", said invention being fully described and/or claimed in the application for Letters Patent of the United States of America, executed this date, in and for the United States and all foreign countries, the same to be held and enjoyed by said assignee, its successors, assigns or other legal representatives, to the full ends of the terms for which all Letters Patent therefor may be granted, as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made.

**And Said Assignee Is Hereby Authorized** to make application for and to receive Letters Patent for said invention in any of said countries at its election.

**And By This Covenant The Undersigned** will execute or procure any further necessary assurance of title to said invention and Letters Patent; and at any time, upon the request and at the expense of said assignee, will execute and deliver any and all papers that may be necessary or desirable to perfect the title to said invention or any Letters Patent which may be granted therefor to said Assignee, its successors, assigns or other legal representatives, and, upon the request and at the expense of said assignee, will execute any additional or divisional applications for patents for said invention, or any part or parts thereof, and for the reissue of any Letters Patent to be granted therefor, and will make all rightful oaths and do all lawful acts requisite for procuring the same or for aiding therein, without further compensation, but at the expense of said assignee, its successors, assigns or other legal representatives.

**And The Commissioner Of Patents Is Hereby Authorized And Requested** to issue any and all Letters Patent of the United States for said invention, to said assignee.

September 12, 2011

Date

Hideto Nakamura

Hideto Nakamura